



**Please note that Cypress is an Infineon Technologies Company.**

The document following this cover page is marked as “Cypress” document as this is the company that originally developed the product. Please note that Infineon will continue to offer the product to new and existing customers as part of the Infineon product portfolio.

**Continuity of document content**

The fact that Infineon offers the following product as part of the Infineon product portfolio does not lead to any changes to this document. Future revisions will occur when appropriate, and any changes will be set out on the document history page.

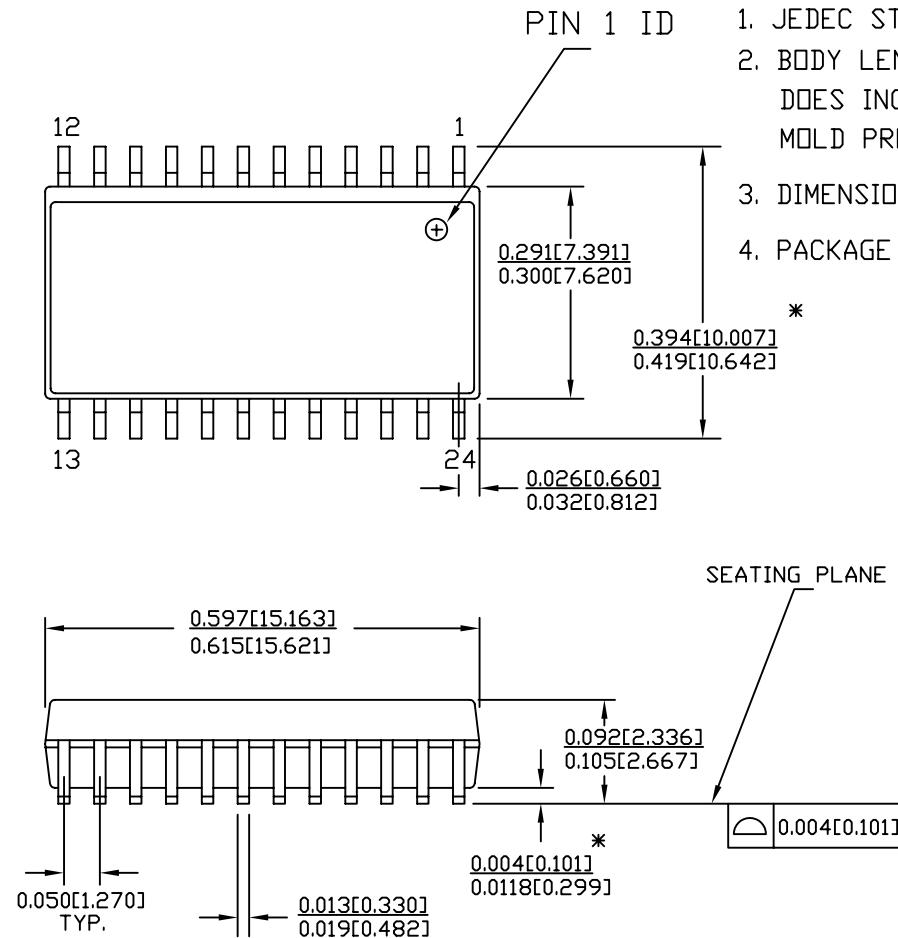
**Continuity of ordering part numbers**

Infineon continues to support existing part numbers. Please continue to use the ordering part numbers listed in the datasheet for ordering.

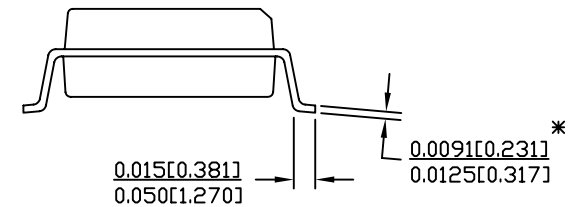
# 24 Lead (300 Mil) SOIC - S13

NOTE :

1. JEDEC STD REF MO-119
2. BODY LENGTH DIMENSION DOES NOT INCLUDE MOLD PROTRUSION/END FLASH, BUT DOES INCLUDE MOLD MISMATCH AND ARE MEASURED AT THE MOLD PARTING LINE. MOLD PROTRUSION/END FLASH SHALL NOT EXCEED 0.010 in (0.254 mm) PER SIDE
3. DIMENSIONS IN INCHES MIN.  
MAX.
4. PACKAGE WEIGHT 0.65gms




PART #	
S24.3	STANDARD PKG.
SZ24.3	LEAD FREE PKG.



THIS DRAWING CONTAINS INFORMATION WHICH IS THE PROPRIETARY PROPERTY OF CYPRESS SEMICONDUCTOR CORPORATION. THIS DRAWING IS RECEIVED IN CONFIDENCE AND ITS CONTENTS MAY NOT BE DISCLOSED WITHOUT WRITTEN CONSENT OF CYPRESS SEMICONDUCTOR CORPORATION.

PACKAGE CODE(S)

SEE NOTE

 <b>CYPRESS</b> Company Confidential	
TITLE PACKAGE OUTLINE, 24L SOIC .615X.300X.0932 INCHES	
SPEC NO. 51-85025	REV *F
SCALED TO FIT	N/A
SHEET 1 OF 2	

Rev.	ECN No.	Origin of Change	Description of Change
**	N/A		N/A
*A	49382		CHG. TITLE/ CHG. DIM.S AT *
*B	128908		ADD MM DIM./ ADD JEDEC #/ ADD SZ PART #/ ADD PKG. WEIGHT
*C	413084		ADD NOTES - JEDEC REFERENCE MO-119 - MOLD PROTRUSION/END FLASH INFORMATION
*D	2868899		CHANGED TEMPLATE, CHANGE TITLE FROM 24LD (300 MIL) SOIC PKG OUTLINE TO PACKAGE OUTLINE, 24L SOIC .615X.300X.0932 INCHES
*E	3146096		ECN SUNSET NO CHANGE
*F	4257179	KTQAD/ XANC	SUNSET REVIEW. CHANGED DRAWING TEMPLATE.



TITLE  
PACKAGE OUTLINE, 24L SOIC .615X.300X.0932  
INCHES

SPEC NO. 51-85025  
REV \*F  
SCALED TO FIT N/A SHEET 2 OF 2

THIS DRAWING CONTAINS INFORMATION WHICH IS THE PROPRIETARY PROPERTY OF CYPRESS SEMICONDUCTOR CORPORATION. THIS DRAWING IS RECEIVED IN CONFIDENCE AND ITS CONTENTS MAY NOT BE DISCLOSED WITHOUT WRITTEN CONSENT OF CYPRESS SEMICONDUCTOR CORPORATION.

PACKAGE CODE(S) SEE NOTE